

Development of Nanostructured Metallic Systems – Progress and Challenges

Presented by

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Ceramic and Metallurgy Technologies

GE Global Research

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#GE Global Research, Bangalore, India

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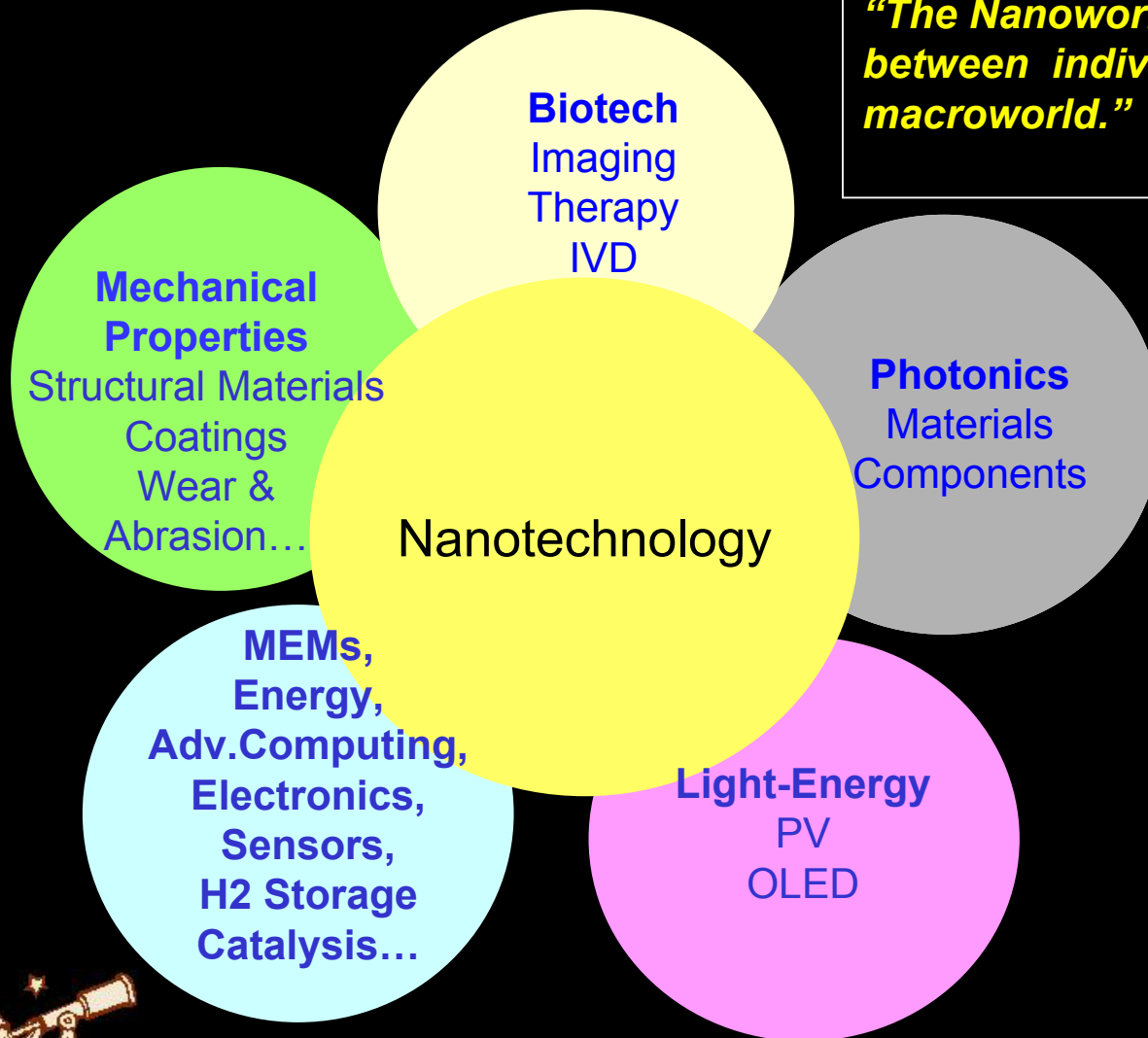
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The Nanotechnology Challenge

“The Nanoworld is a weird borderland between individual molecules and the macroworld.”

Scientific American, 9/01



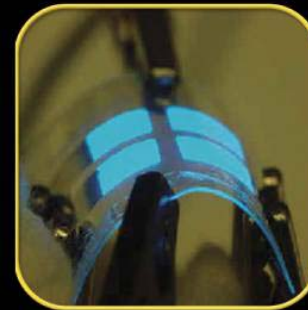
Too Many Opportunities: Where do we start?





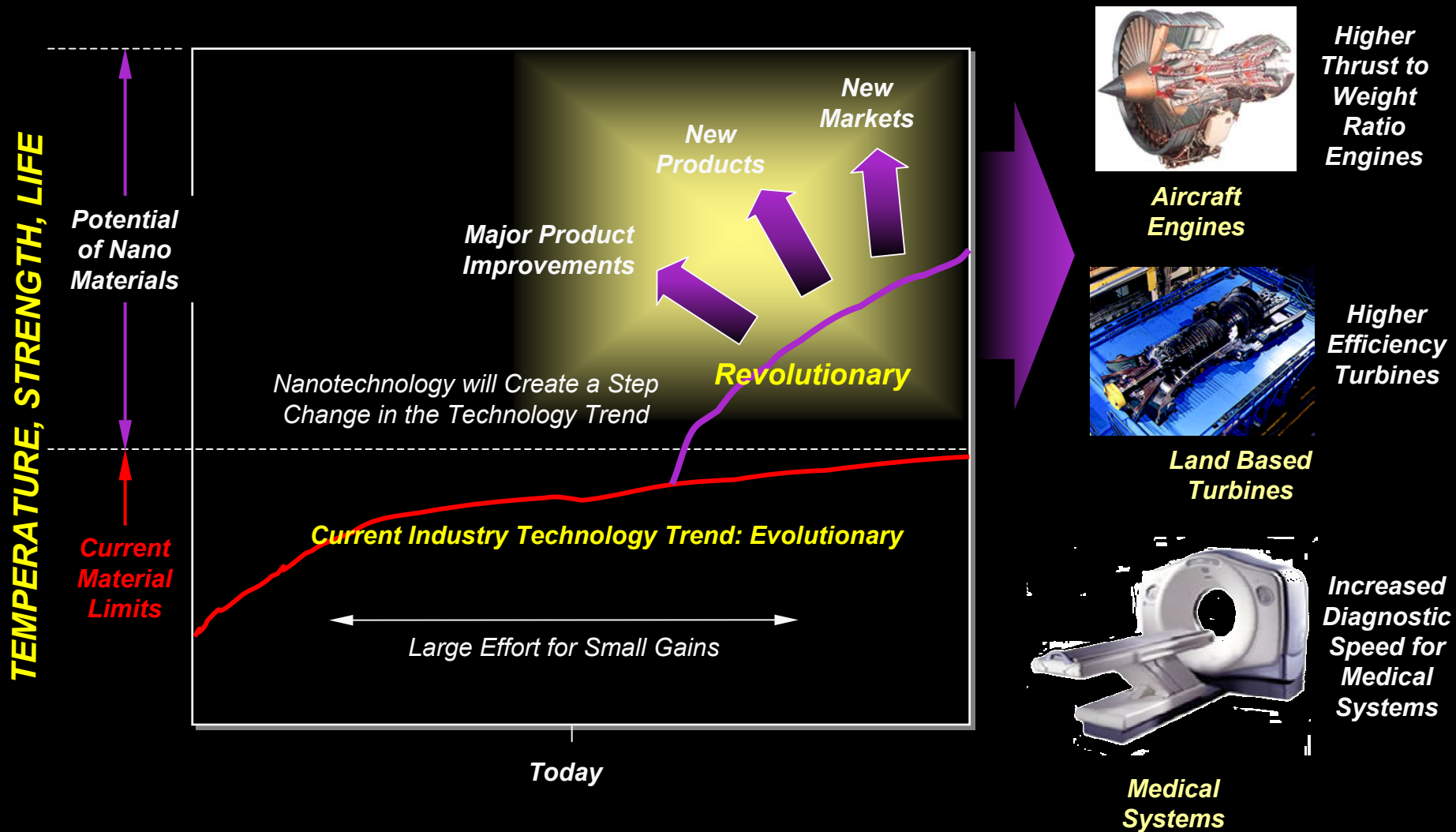
GE Technology...

- Saving Energy & the Environment
 - GE Aircraft Engines, GE Power Systems, GE Specialty Materials, GE Industrial Systems, GE Transportation
- Household Innovations
 - GE Consumer Products, GE Plastics
- The Future of Healthcare
 - GE Medical Systems





Why is GE Investing in Nanotechnology?

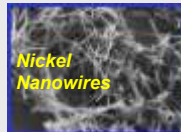


All of the GE Businesses will benefit from the current investments being made in nanomaterials and nanotechnology

NanoMaterials

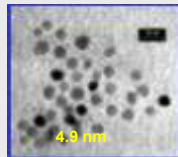
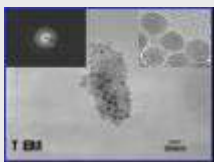
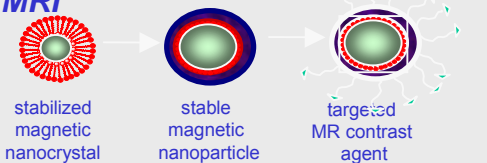
Nanotubes & Nanowires Platform

Leverage existing & invent novel materials in targeted application areas



Magnetic Nano-Particles Platform

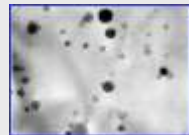
Develop expertise in functionalized magnetic nanoparticles via contrast agents for MRI



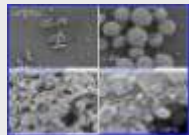
NanoComposites

NanoStructures in Metals & Ceramics Platform

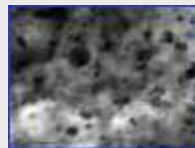
Develop fundamental structure-property relationships to design novel structural materials



ODS Alloys



Thermal Spray

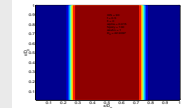
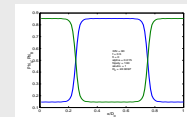


EB-PVD

Ordered NanoStructures

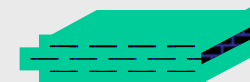
Hybrid Materials Platform

Exploit self-assembly to engineer complex organic/inorganic systems



Ceramics Platform

Leverage biomimetic syntheses to produce high toughness, high T structural ceramics



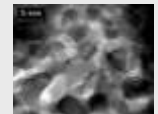
Soft Lithography, Micro-casting
(0.1-1mm)



Field Induced, Sol-gel
(1-10 μ m)



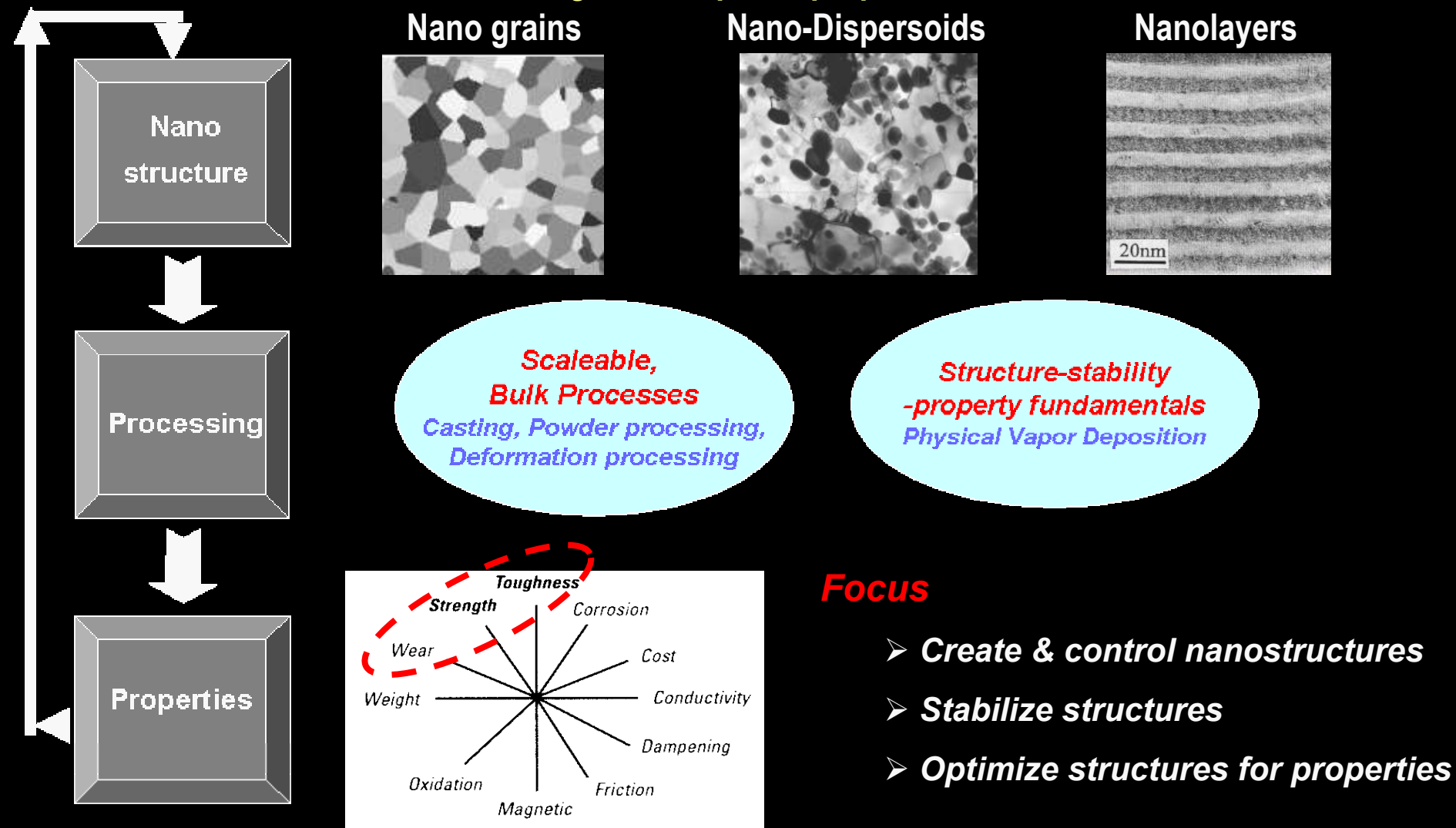
Surfactant / Polymer Based Synthesis
(~10 nm)



Broad Based Materials Foundation

Nanostructured Metallic Systems

Develop fundamental structure-property relationship to design nanostructural materials & coatings with superior properties

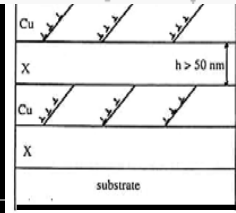
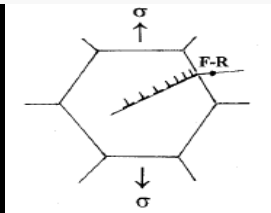
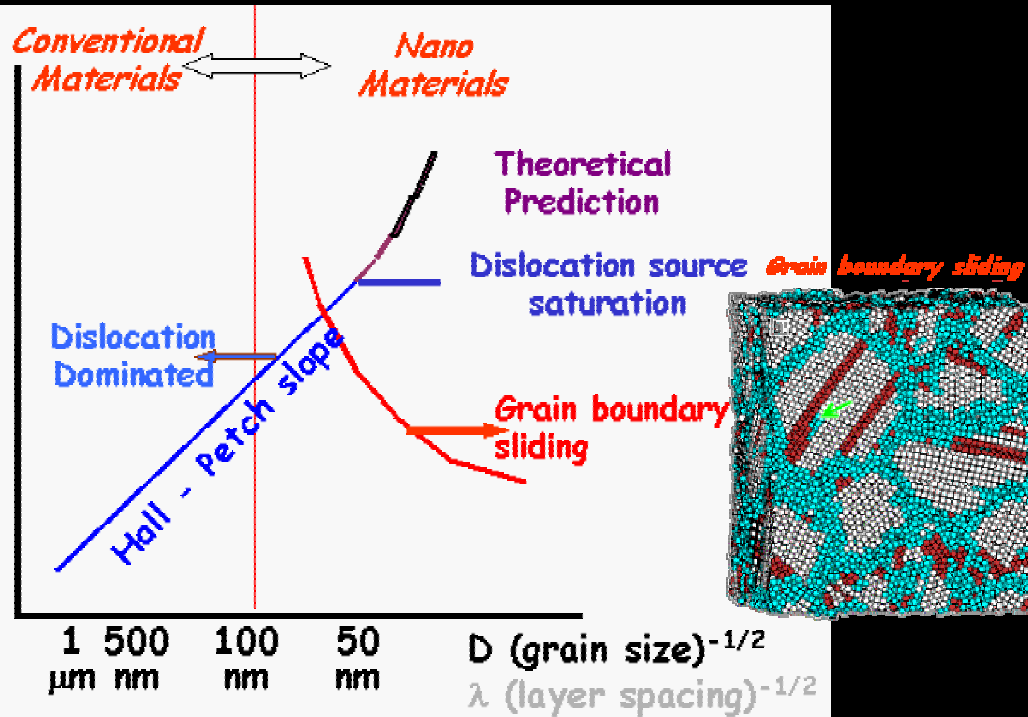


Opportunities for exceptional stability & strength enhancement in metallic materials

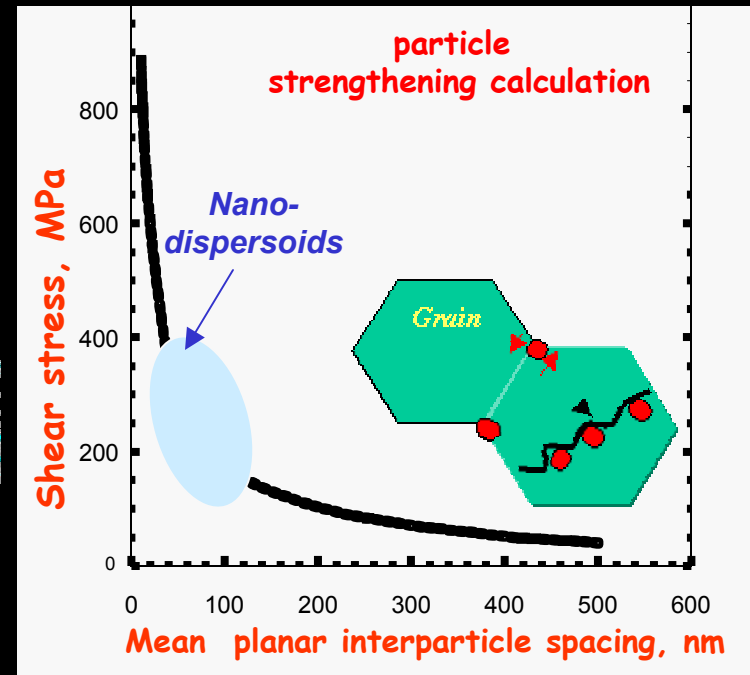


Strengthening Mechanisms

Effect of Microstructural Scale

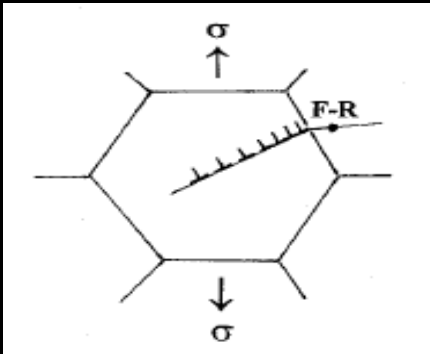


Effect of Dispersoid Reinforcement



Order of magnitude increase in strength over micron size predicted

- Issues:**
- Dislocation source saturation at nano-scale
 - Competition between strengthening from nano-scale vs. weakening by gb sliding
 - Thermal stability

**Single phase Nanocrystalline Materials**

- Large grains: many dislocations in pile-up → continuum theory of Hall-Petch works ($\sigma \propto d^{-1/2}$)
- Small grains: question is how many dislocations in pile-up?

of dislocations in pile-up
(using circular pile-up model)

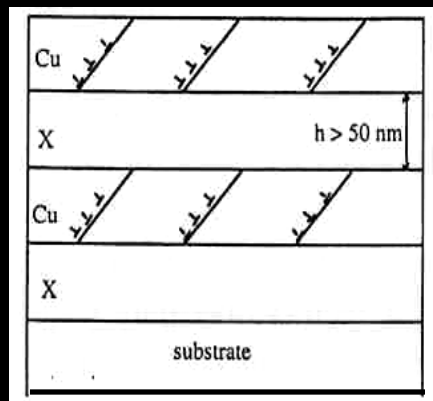
$$n = \left(\frac{\tau^*}{G} \right)^{1/2} \left(\frac{D}{b} \right)^{1/2}$$

~20-100 nm grain size: dislocations cross gbs one at a time & there is no pile-up (dislocation source saturation)

→ Easier to deform by Coble creep instead of dislocation glide

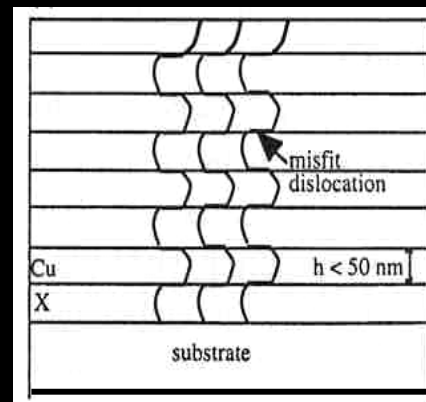
Layered Structures

Large h ($\lambda/2$)



Hall-Petch behavior - dislocation pile-ups at interface

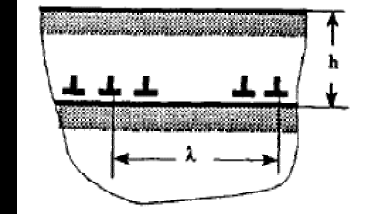
Small h ($\lambda/2$)



Plastic flow by single dislocations moving by bowing within layers



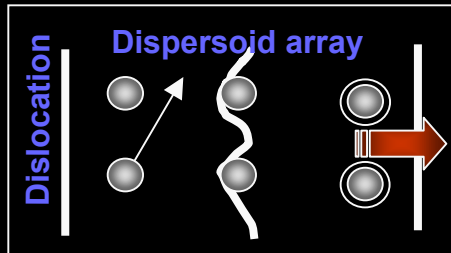
Misfit dislocations in multilayers



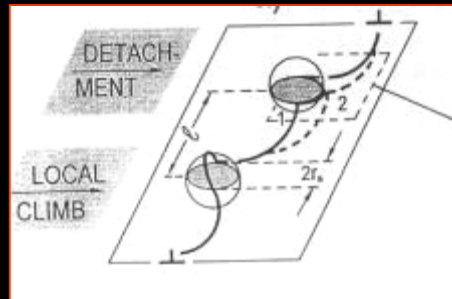
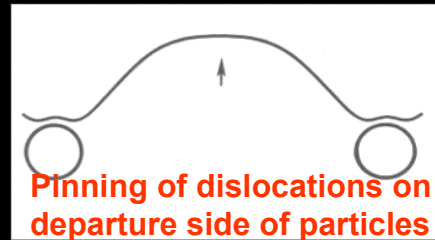
Leaves misfit dislocations at interface



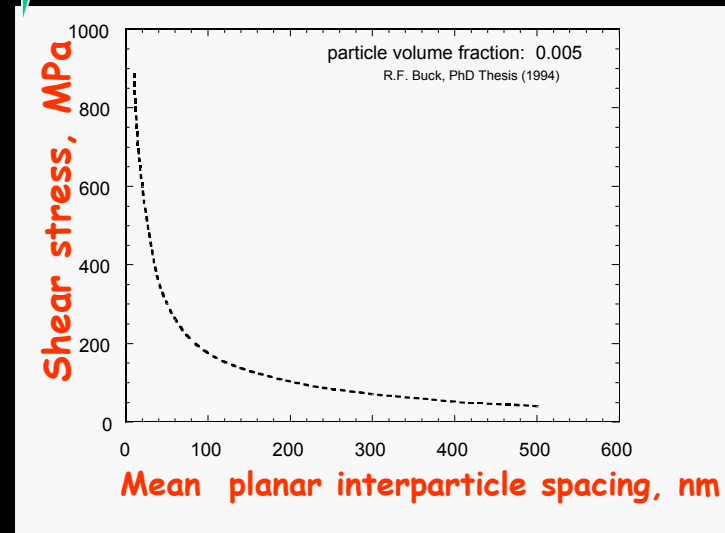
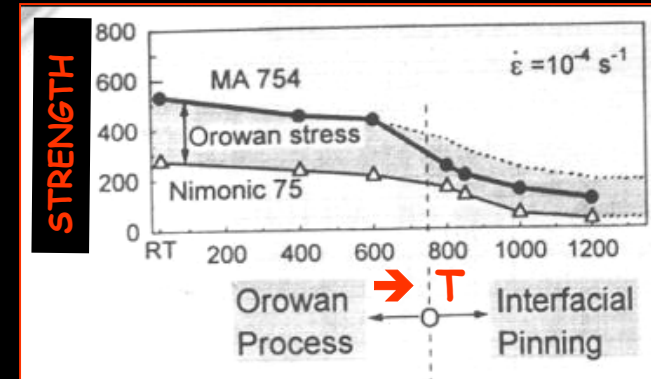
Dislocation-particle interactions



Orowan mechanism



Interfacial pinning mechanism



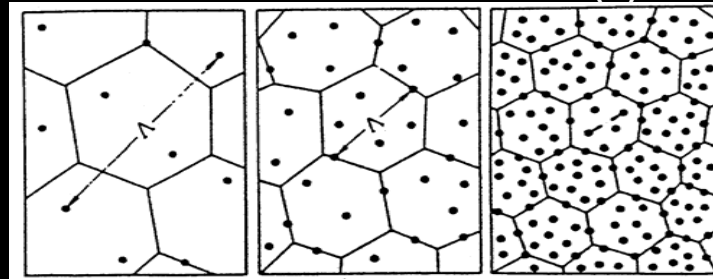
Issues:

- Thermally assisted climb at high T_s
- Microstructural stability at high T_s and high stresses
- Dispersoid volume fraction: Tradeoff for strengthening vs. ductility ?
What is needed for wear resistance?



Dispersoid Reinforcement - Grain Boundary Pinning

Grain Size (D) vs. Mean Free Path (Λ)
Between 2nd Phase Particles (d)



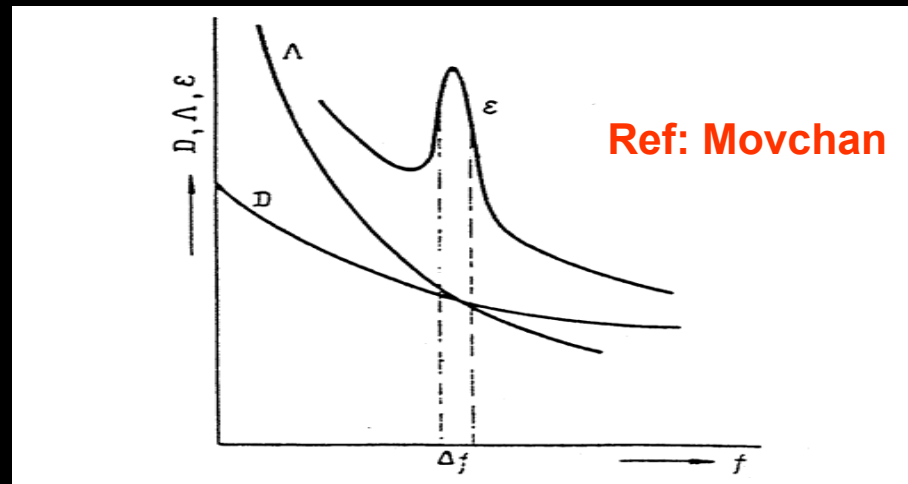
$D < \Lambda$

$D = \Lambda$

$D > \Lambda$

INCREASING DISPERSOID CONTENT →

Zener Pinning



Issues:

- Microstructural stability at high T s and high stresses
- Dispersoid volume fraction: Tradeoff for strengthening vs. ductility? What is needed for wear resistance?



Dispersoid Structures

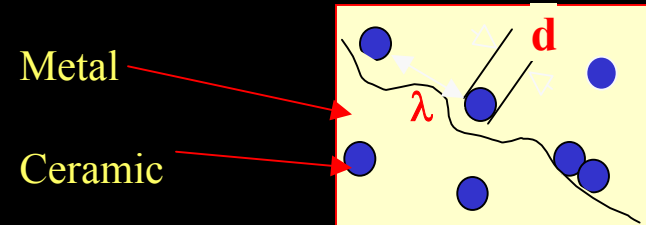
Nano strengthening mechanisms can be used to leverage superior wear properties while retaining higher toughness

$$\text{Wear} = f(H, K_c)$$

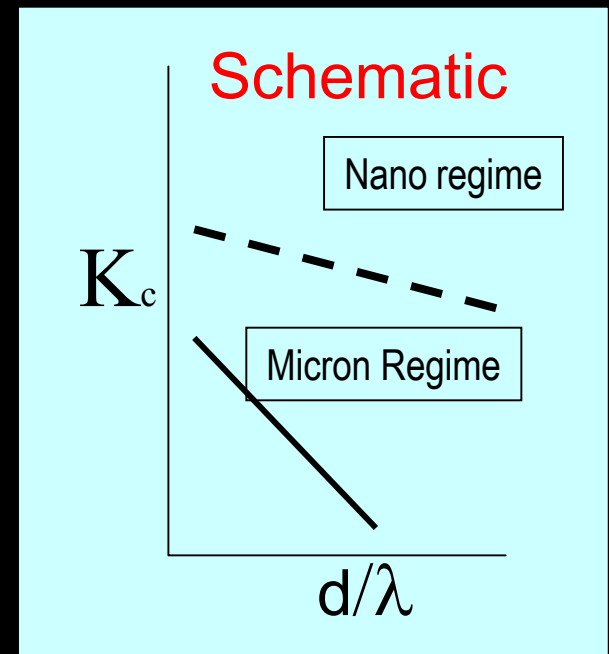
$$H = \text{Hardness: } f(\lambda^{-1/2})$$

$$K_c = \text{Fracture toughness: } f(\lambda/d)$$

- *Higher hardness through lower mean free spacing λ*
- *Better toughness through fine particle size d , and d/λ ratio*



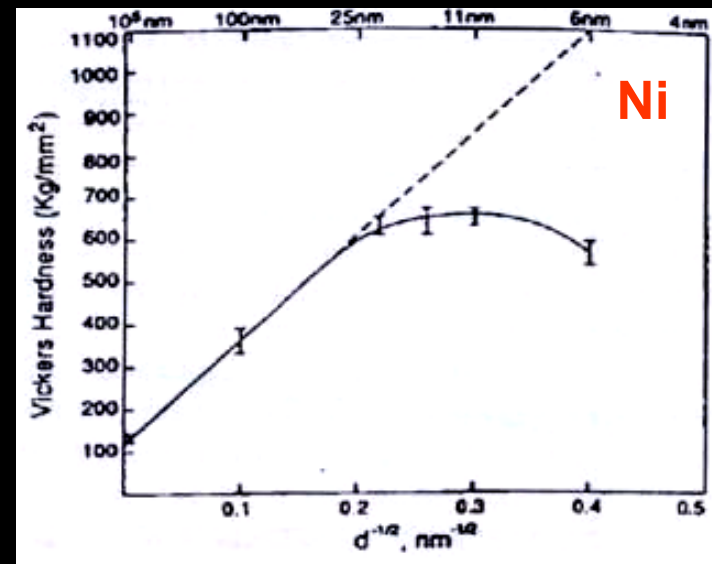
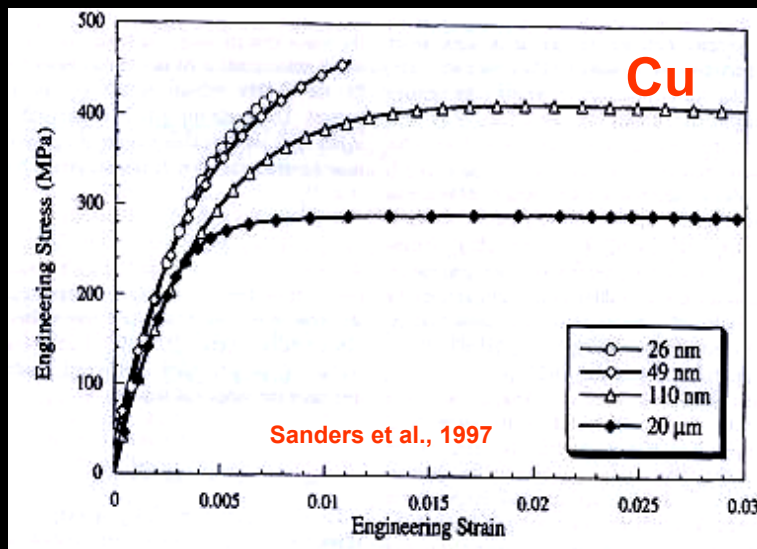
7 X reduction in wear by reducing λ from 0.4 to 0.15 microns



High wear resistance and toughness obtained by dispersoid structure



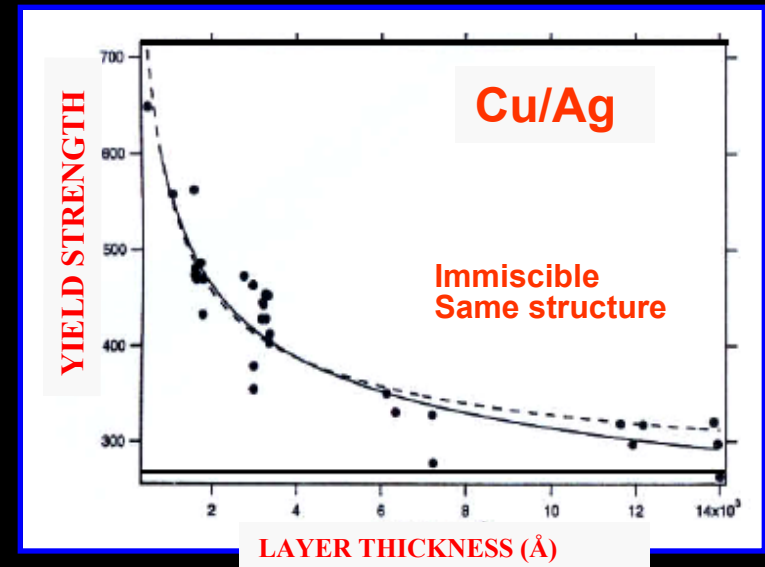
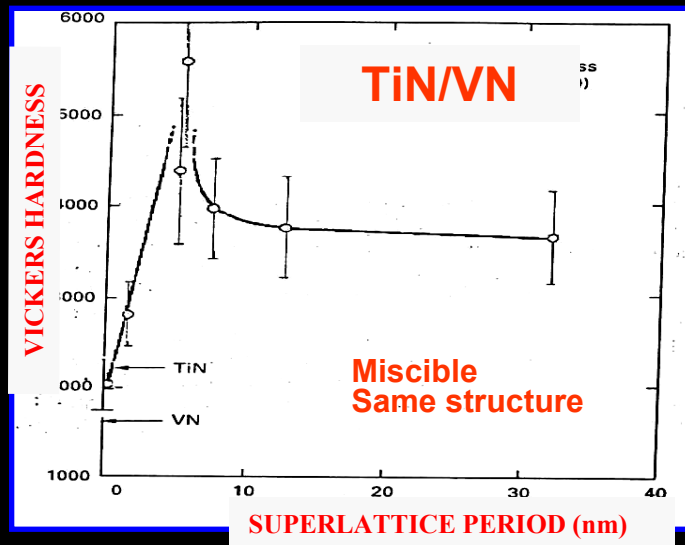
- **Strength (nanocrystalline metals) >> Strength (conv. metals)**
- **Ductility (nanocrystalline metals) << Strength (conv. metals)**
- **Hardness & wear resistance = strong function of g_s**
- **Modulus & thermal expansion = mostly grain-size independent**
- **Softening at ~ 5-50 nm grain size due to grain boundary sliding + diffusional creep**
- **Properties = strong function of processing**





Parameters influencing strength

- Layer spacing (λ)
 - Large spacings: Hall-Petch behavior (Dislocation pile-up model)
 - Low spacings: individual dislocation motion in layers
 - Very low spacings: superlattice strength (\gg harder component)
- Miscibility
- Slip systems (Crystal structure)
- Shear modulus
- Coherency strains (δ)



- Metal/ceramic multilayers show good combination of toughness + hardness
=> wear application
- Significant strengthening observed in nanolayered structures



	Dispersed Structures			Layered Structures			
Mechanisms/Factors	Strength	Creep	Thermal Stability	Strength	Creep	Thermal Stability	Parameters
Dislocation-particle interaction (Orowan effect, attachment, detachment, shear)	√	√					Particle size, spacing, distribution
GB-particle interaction (Zener pinning)	√	√					Particle size, spacing, distribution
Hall-Petch effect (Dislocation-boundary interaction)	√			√			Matrix grain size /layer spacing
Grain boundary sliding	√	√	√				Matrix grain size & aspect ratio
Microstructural Evolution	√	√	√	√	√	√	Thermo/kinetics
Interfacial energy		√	√		√		
Dislocation sources & generation stresses	√?			√			Matrix grain size /layer spacing
Dislocation substructure	√						Matrix grain size
Koehler Stress or Image Stress				√			Modulus mismatch
Interface coherency	√			√			Crystallographic mismatch
GB segregation of solutes & particles	√	√	√				
Miscibility	√		√	√		√	Solubility/diffusivity/ Thermodynamics

GOAL: Differentiate mechanisms giving rise to unique properties



Stability

Predictive tool development

- Phase Field
- Analytical

§ Grain growth
§ Alloying effects on stability
§ Thermal stability of layered structures
§ Exptl. validation

Atomistics

Strengthening mechanism prediction & fundamental quantities

- Embedded Atom Method
- Analytical

§ Interfacial strength
§ Dislocation-interface interaction mechanisms
§ Exptl. validation

Mechanical Behavior

Deformation behavior understanding

- Analytical
- Numerical

§ Nano-structural effects on deformation behavior
§ HT creep mechanisms in nanostructures

Modeling across multiple-length scales for structure-to-property understanding in metallic nanostructures



Dispersed

Structural
Alloys

Multilayers

Metal/Metal
Metal/Ceramics

Functional
Coatings

**Create
nanostructures**

**Scaleable,
Bulk Processes**

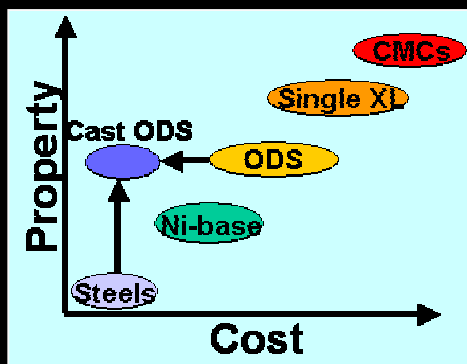
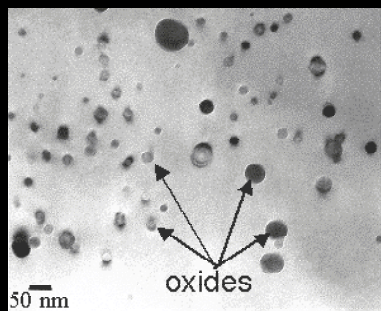
*Casting, Powder processing,
Deformation processing*

**Structure-stability
-property fundamentals**
Physical Vapor Deposition

Produce controlled & tailored systems for structure-property understanding
Learn what controls grain growth; high T stability; gb sliding



Objective: Develop technology for dispersion of nano oxides in molten metal castings.



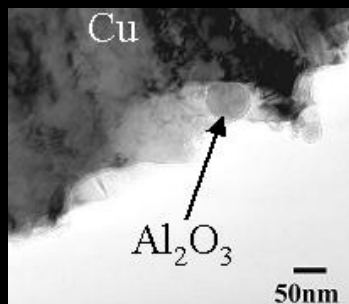
Opportunity

- Lower cost
- Higher strength
- Higher T capability

Technical Barriers:

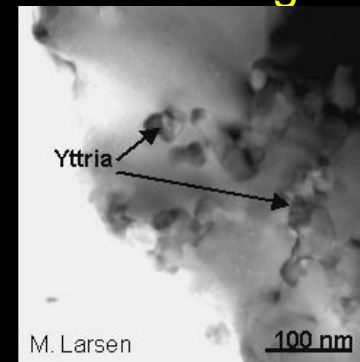
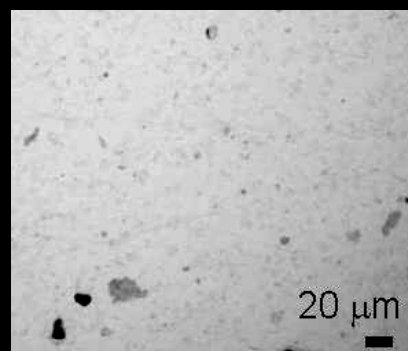
- *Wettability & reactivity at particle/matrix interface*
- *Dispersion, initially and during solidification*

Power feedstock



Coat feedstock

Melt and Solidified casting



Agglomerated n-yttria + detached n-oxides

Dispersion Technologies

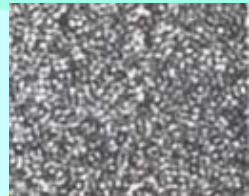
- **Coatings**
- Active Elements

Initial results showed some wetting and dispersion of nano-oxides in molten metal



Bulk Amorphous Phase

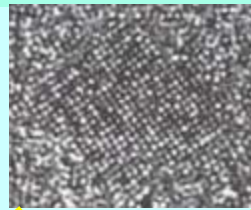
- Non-crystalline
- Isotropic
- No segregation
- Producible in bulk by conventional methods



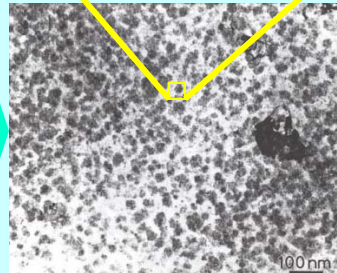
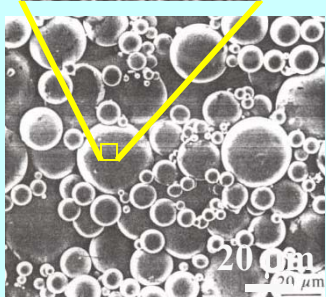
+ Heat Treat =

Nano-crystalline Materials

- Ultra-fine grains
- Uniform distribution
- Nano-particles
- Varieties of primary/second phases possible

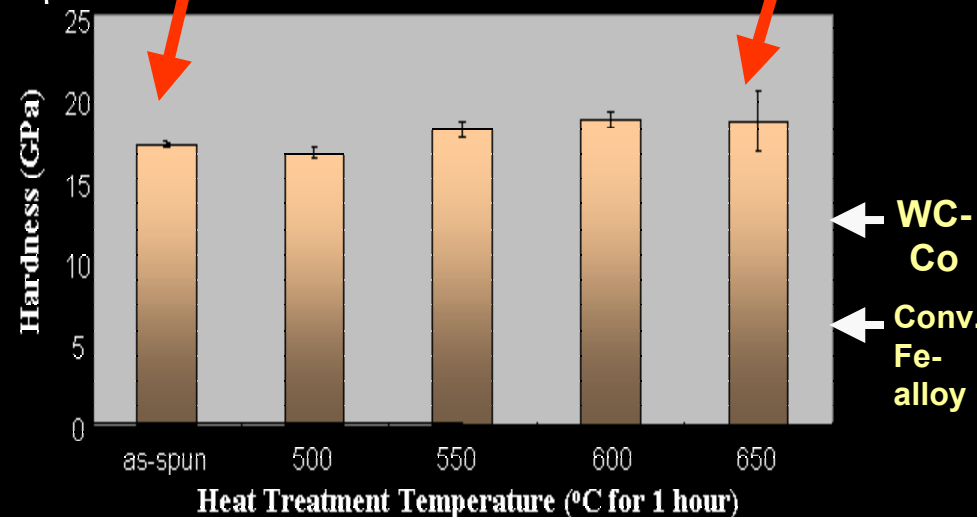
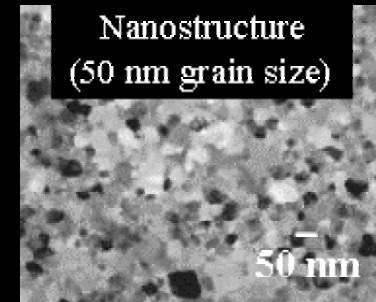
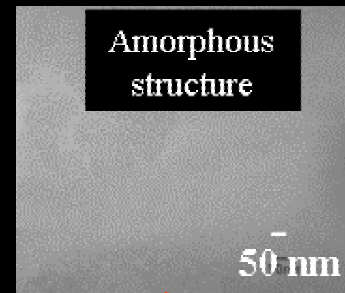


Powder Deposition, Consolidation



- High Strength
- Corrosion Resistant
- Damage tolerant

Nanostructured Fe-Based Materials

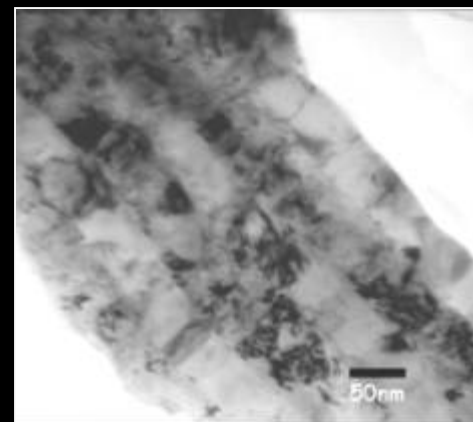
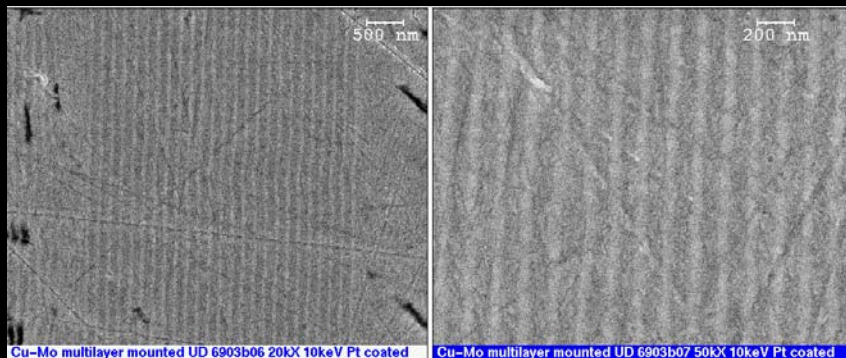


Nanostructures created in Fe-based alloys exhibit hardness 4x conventional alloys

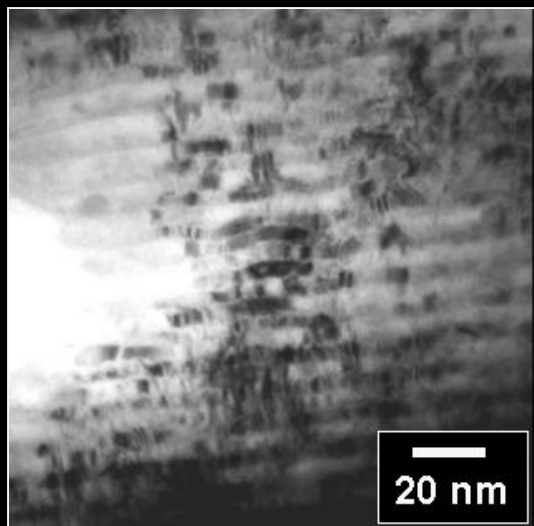


Layered Structures by PVD

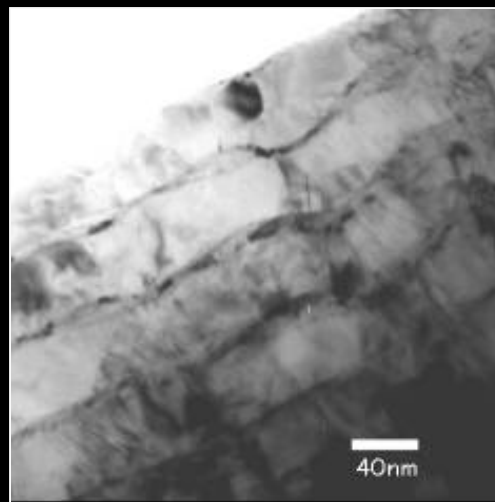
(50nm Cu/50nm Mo) \times 50



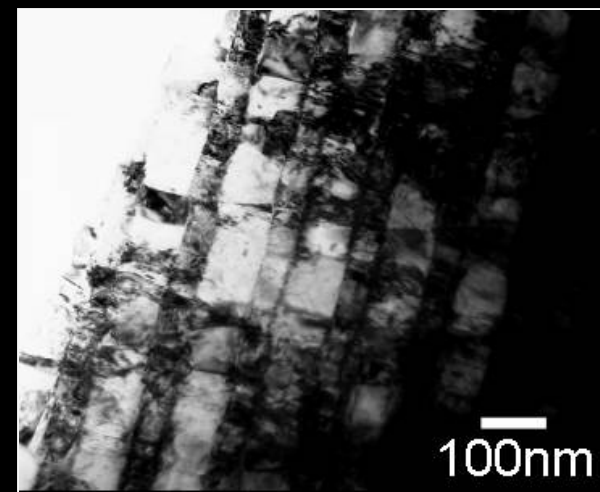
(5nm Cu/5nm Mo) \times 50



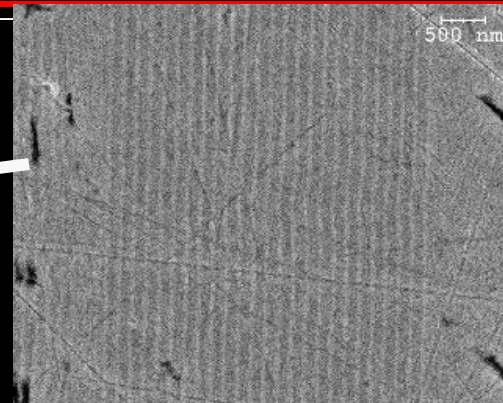
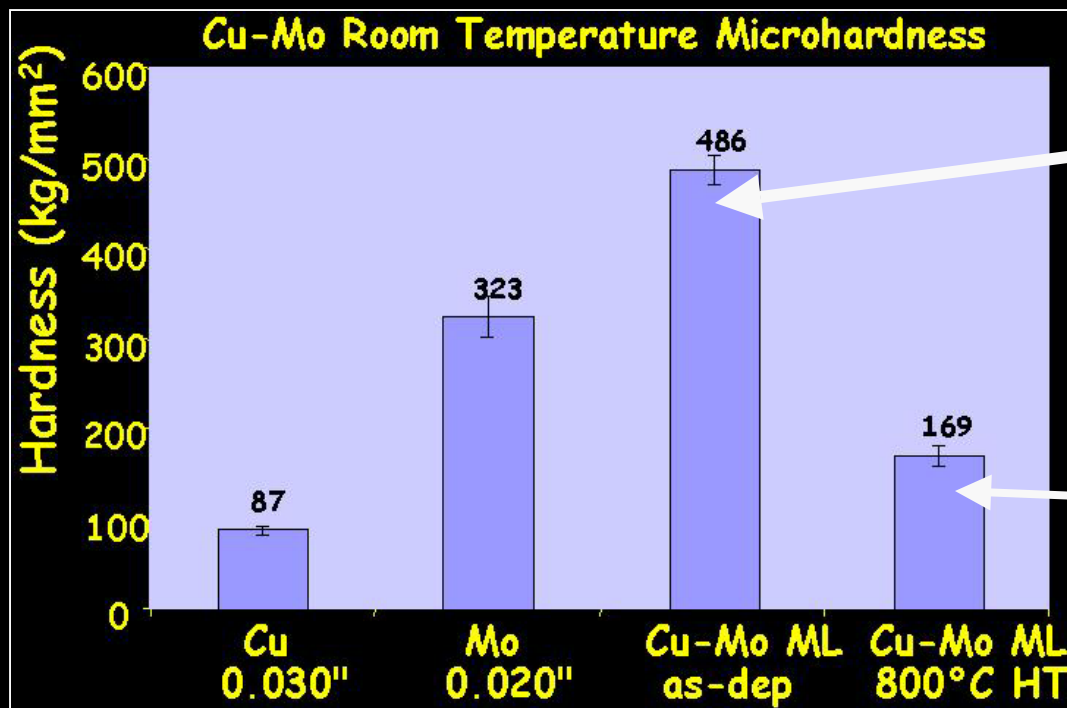
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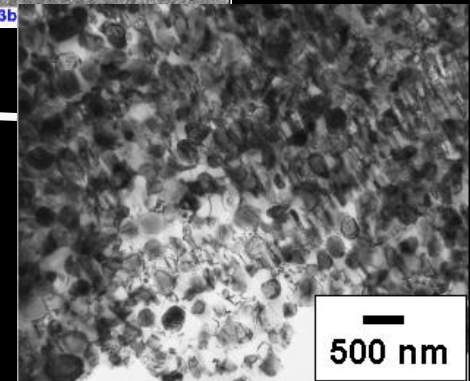
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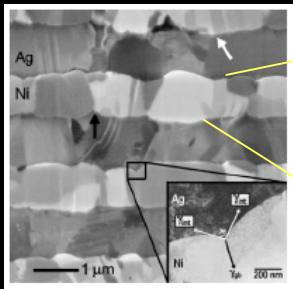
- **Controlled nanolayer systems can be fabricated by PVD**
- **Experiments planned to study variables affecting strength in layered systems**



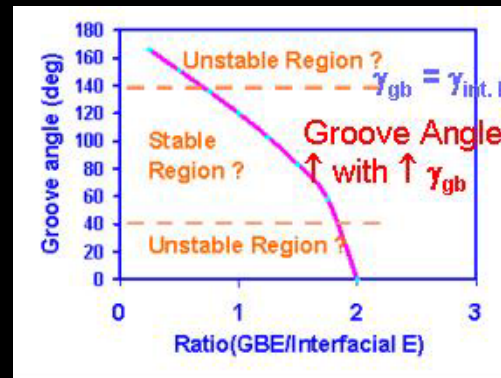
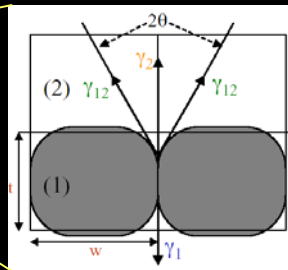
Cu-Mo multilayer mounted UD 6903b



500 nm



**Thermal
grooving
of GB**



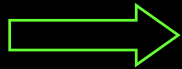
**Need predictive model
for thermal stability
from microstructural
variables**

Stability Diagrams

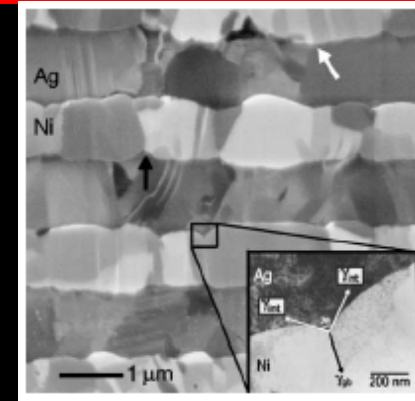
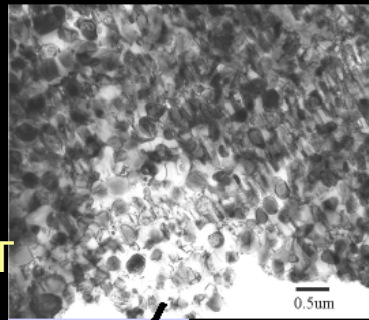
- Significant increase in hardness demonstrated in nano multilayers
- ~60% drop in strength for unstable spherodized structure



Cu-Mo



800°C HT

**Kinetic Model:****Evolution of groove depth 'd' with time 't' :****Thermal stability of Multilayers :**

→ Instability mechanism: thermal grooving

$$d = (0.78) (\tan \beta) [(\Omega^{4/3} D_{\text{int}}) \frac{\gamma_{\text{int}}}{kT}]^{1/4} t^{1/4}$$

For a (50 nm/50 nm) Cu-Mo multilayer, time taken for grooving :

T= 800°C → time ~ 0.006 h

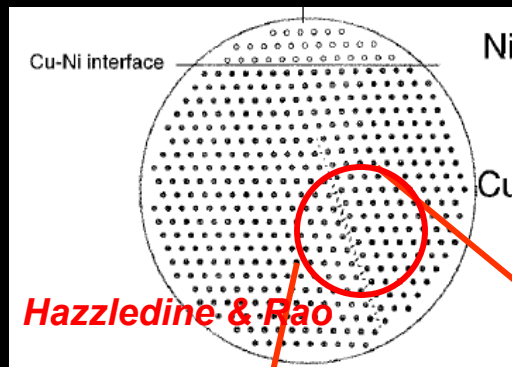
T= 500°C → time ~ 0.16 h

T= 300°C → time ~ 12 h

Refinements Needed:

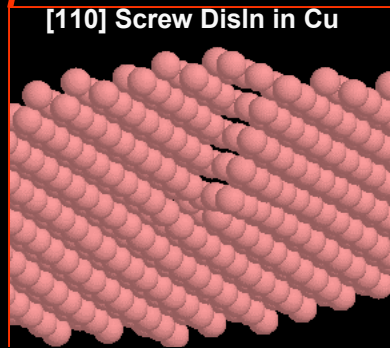
- **Interface Diffusivity of Cu-Mo**
- **GBE/interfacial energies dependence with T**

- **HT & TEM to determine groove angle in Cu-Mo multilayers**
- **Refinement of kinetics model needed**

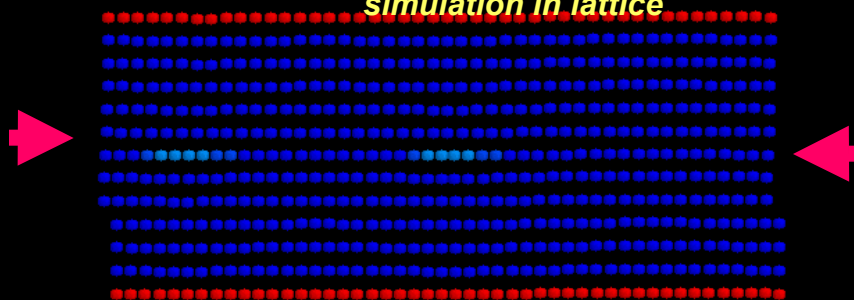


Hazzledine & Rao

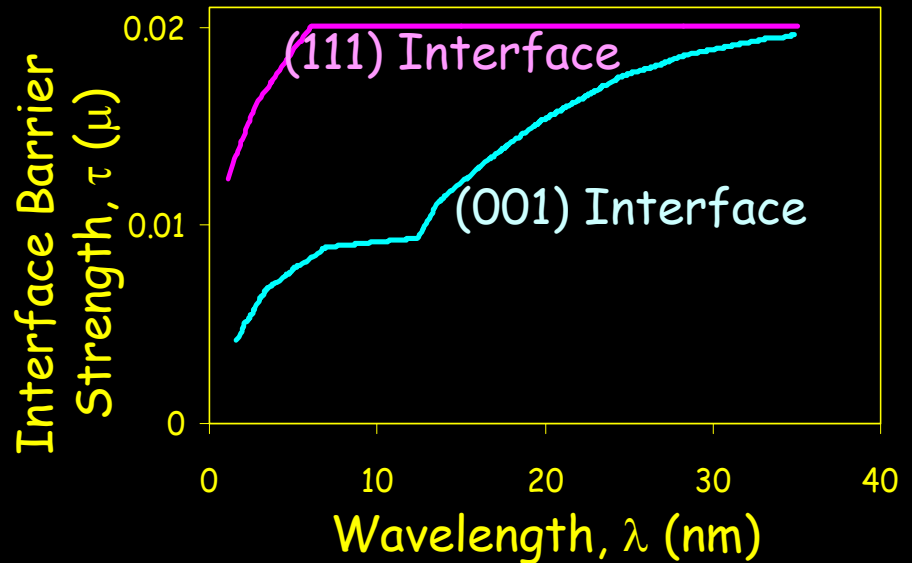
Dislocation vs. Interface in Nanolayers



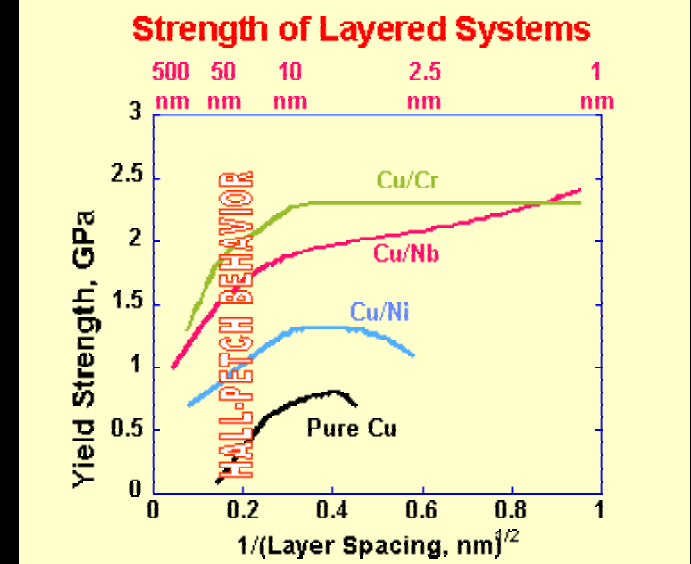
[110] Screw Disln in Cu
Dislocation simulation in lattice



Dislocation motion under applied stress in Ni lattice



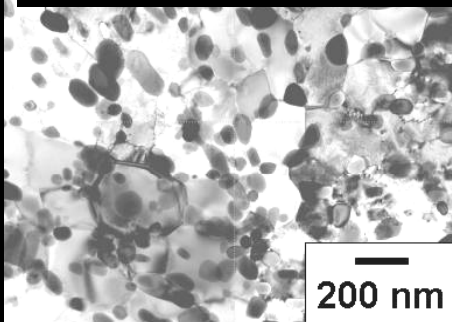
Literature data on layered systems



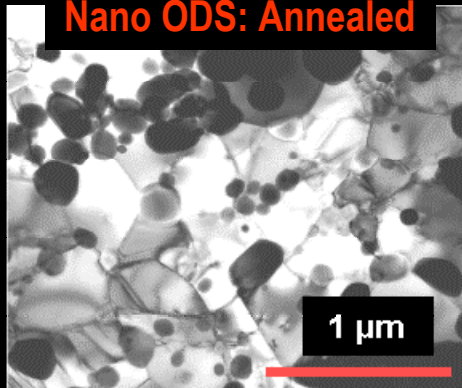
GOAL: Prediction of strength in nanolayered structures



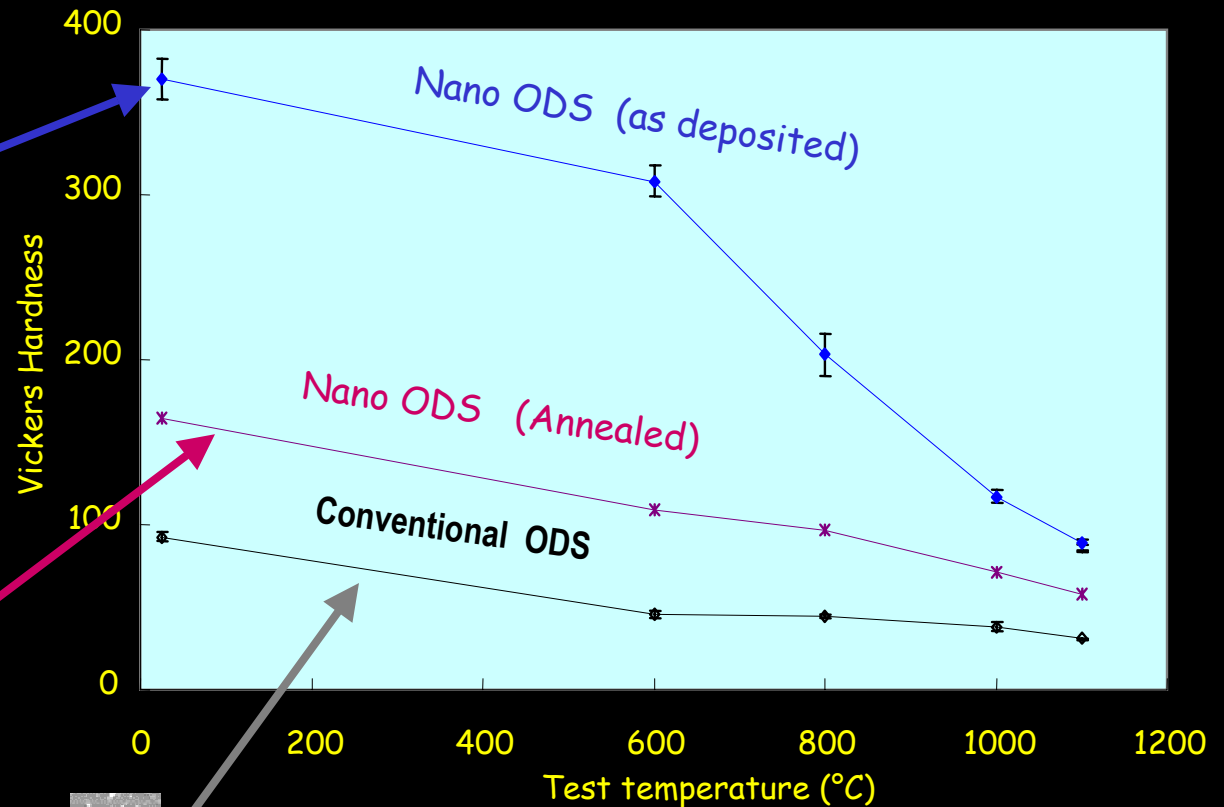
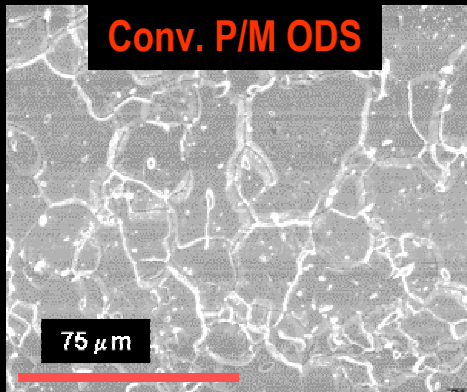
Nano ODS:as deposited



Nano ODS: Annealed

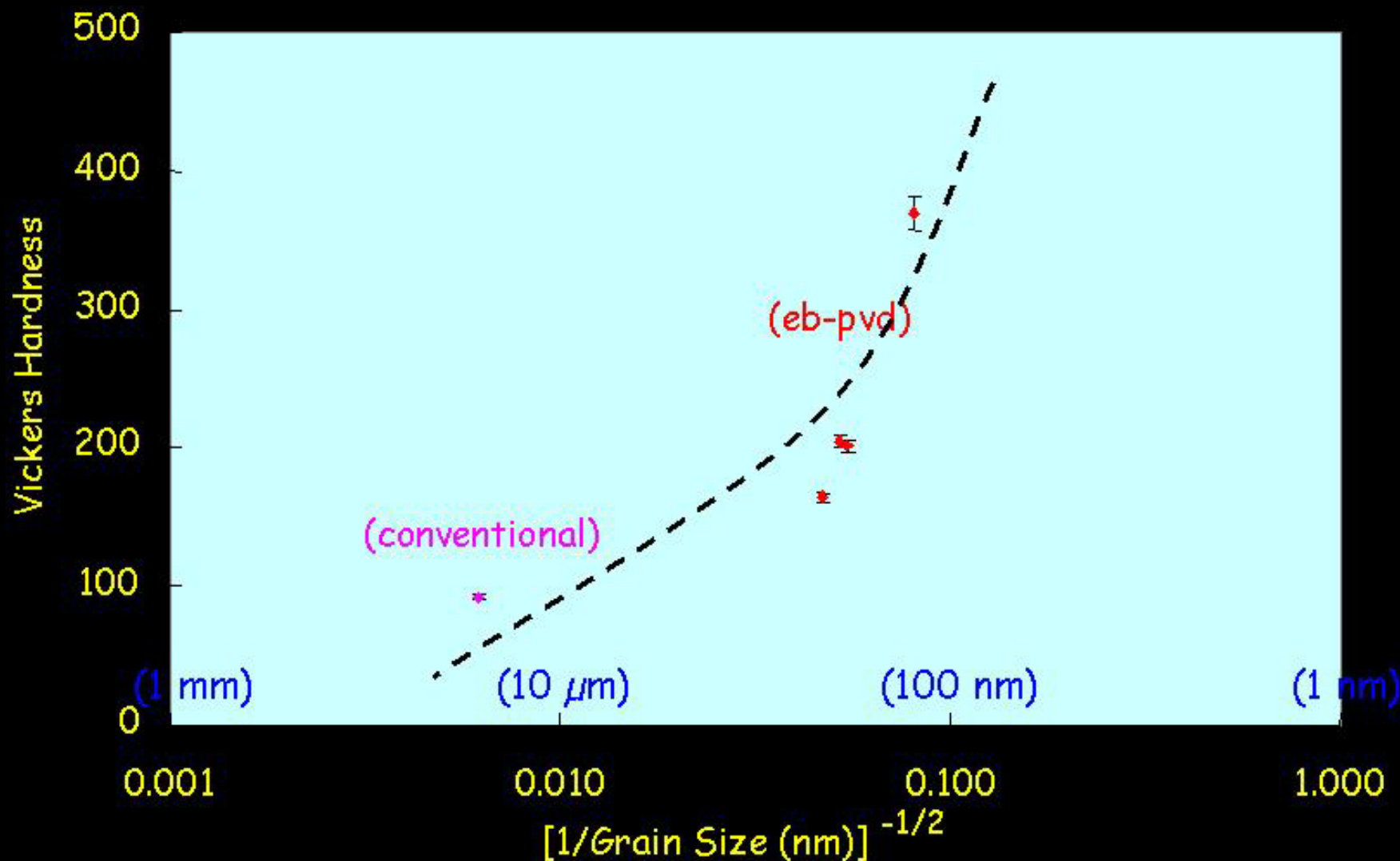


Conv. P/M ODS



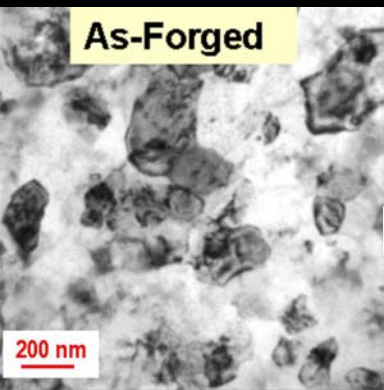
- Nano ODS structures over 2 times harder than conventional ODS structures

- Nano ODS stronger than conventional ODS at all temperatures

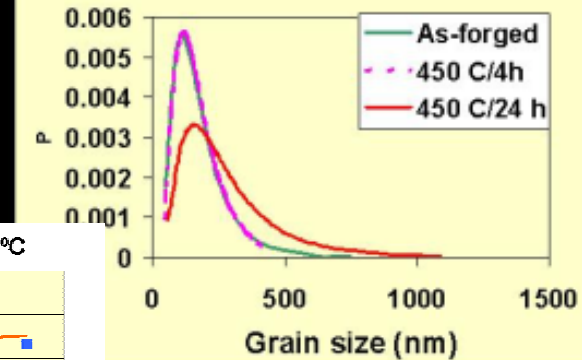
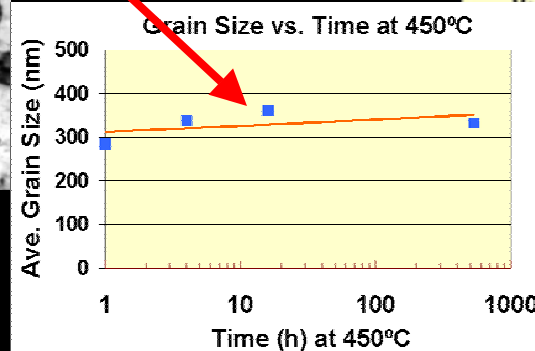
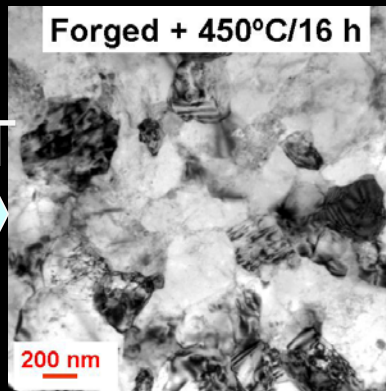


Nano ODS has ~2-3x greater hardness (strength) than conventional material

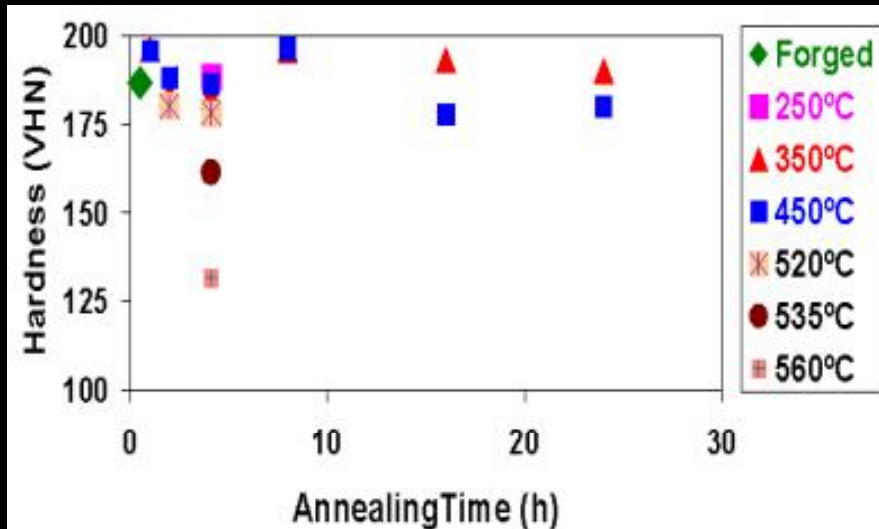
Mechanically Alloyed Nano-Al



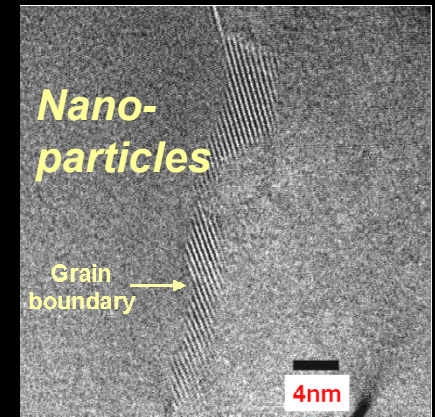
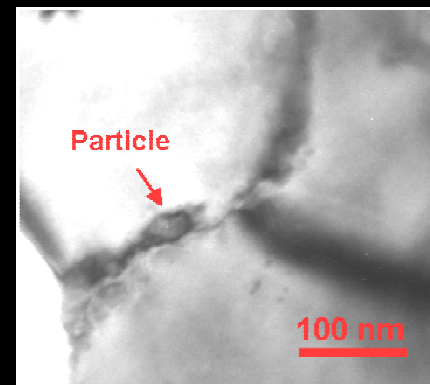
HT



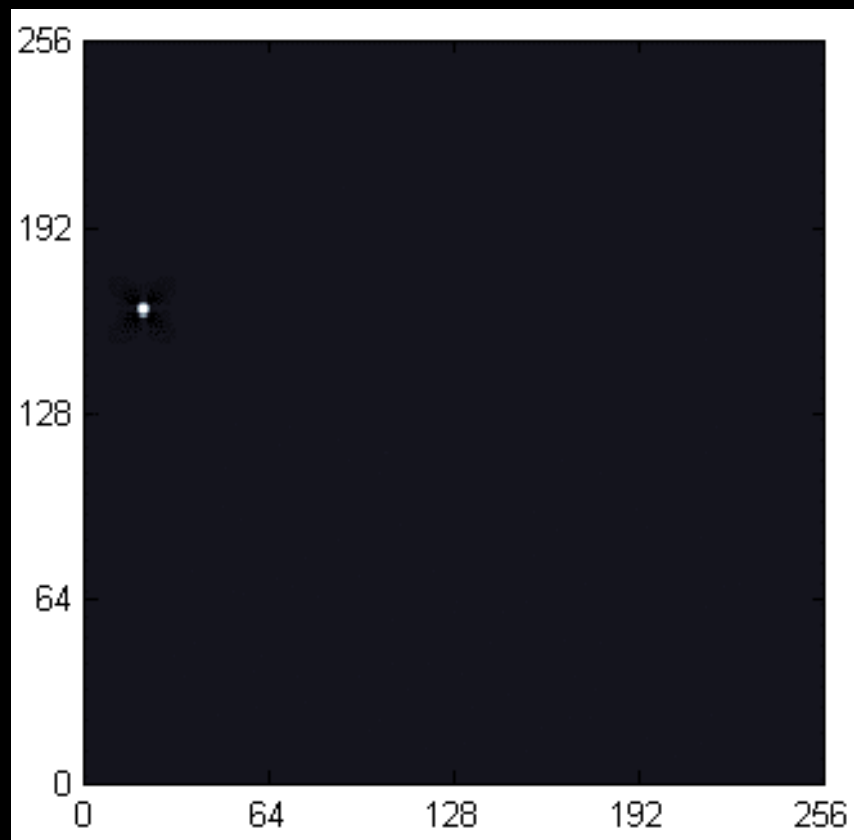
RT Hardness
vs. Annealing Temperature & Time



Grain Boundary (GB) Pinning by
Particles: Zener Pinning?

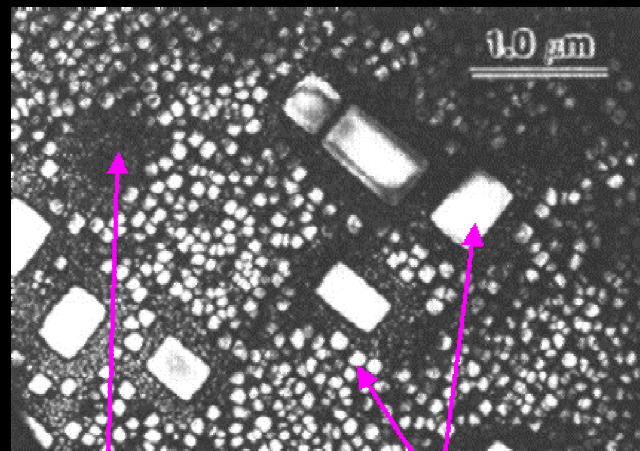


Early stages of understanding of potential stability mechanisms in Nano-Al



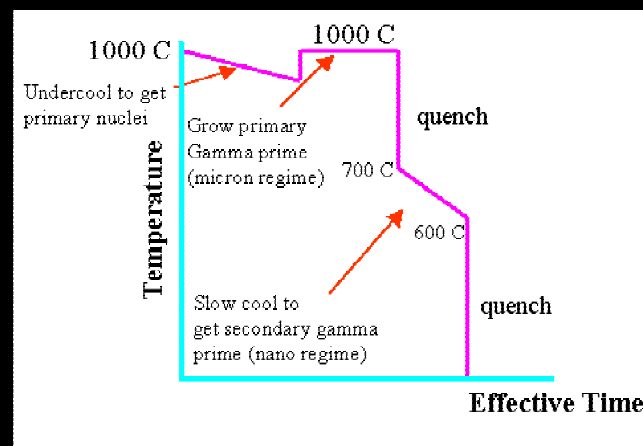
150nm

Experimental structure
Micron and nano scales



Ni matrix

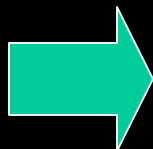
Ni₃Al precipitate



Phase-field approach is applicable at micron and nano size scales

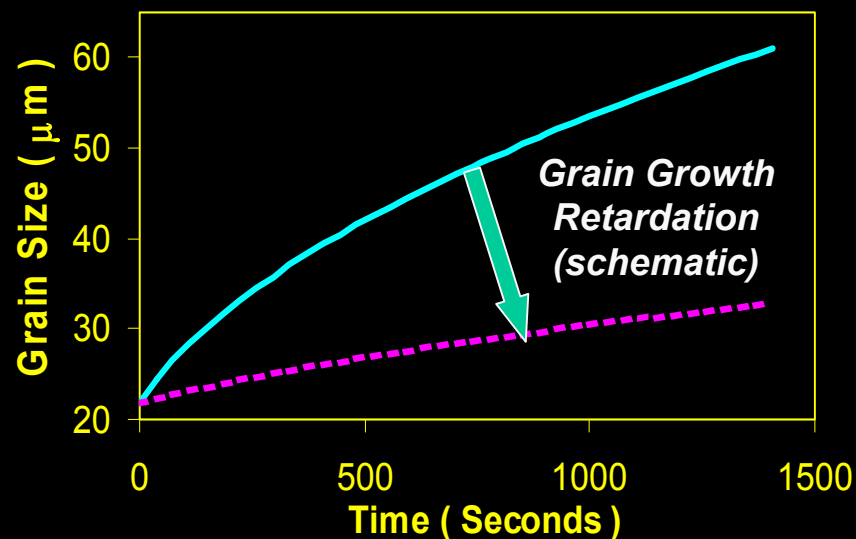
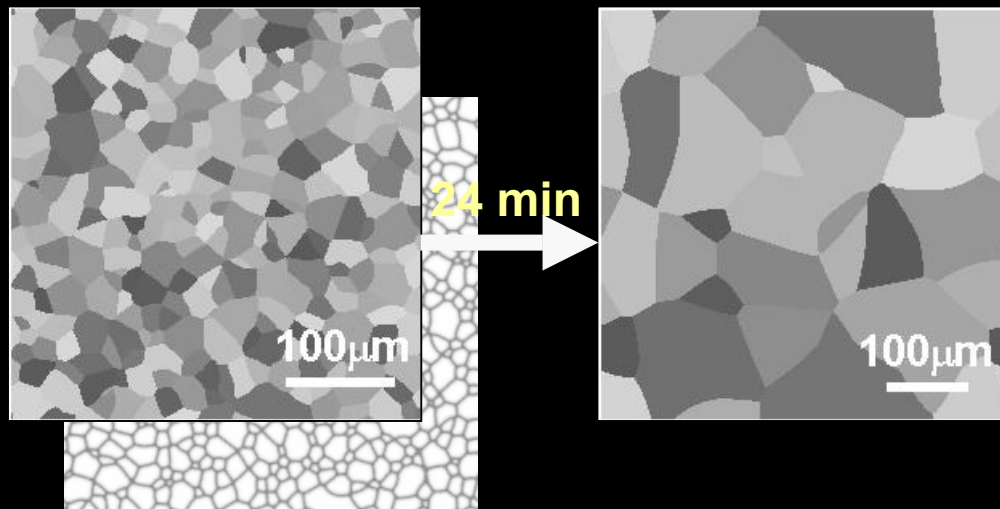


Thermodynamics
Diffusion
Strain energy
Surface Energy
Morphology



- *How much of second phase (V_f)*
- *Size (d_p)*
- *Shape*
- *Crystal structure & orientation relationship*
- *Stability*

Initial modeling efforts: Ni @ 800 °C

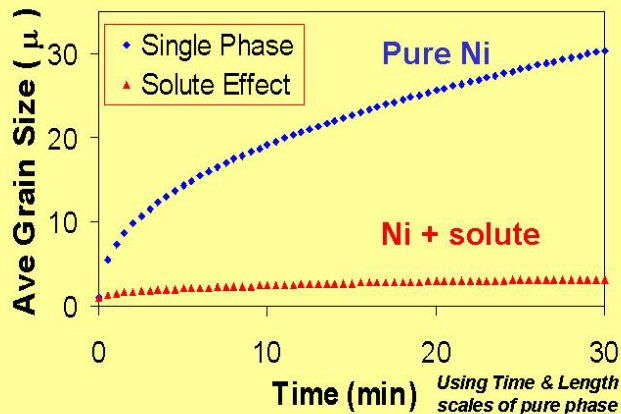


Grain growth model in place for predicting thermal stability of nano-structures

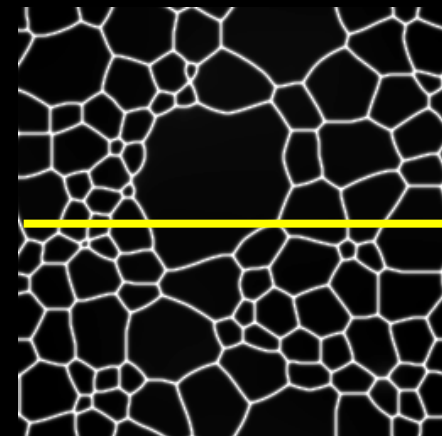


**Grain growth in pure Ni:
Model vs. Validation**

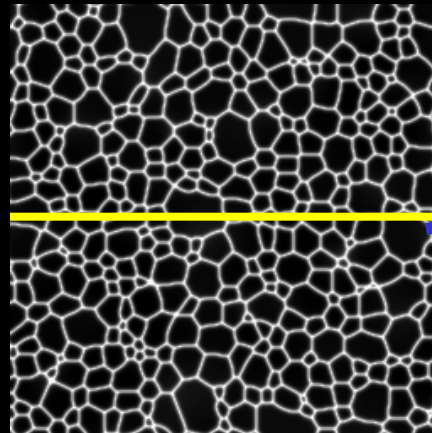
T (°C) / t (min)	Grain Size (μ) Starting GS = 16.4 μ	
	Model	Expt
800/30	35.5	35.1
800/60	44.2	37.9
1000/30	102.1	91.9



Model solute
Diffusivity = $\frac{1}{2}$ (self diffusion of Ni)



Norm. time = 5000 (0.3 s)

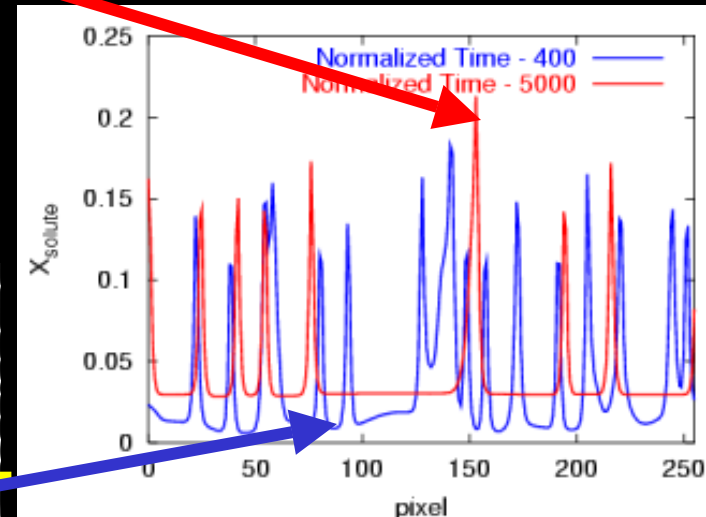


Norm. time = 400 (0.02 s)

1μm

Solute Segregation (at%)

$\tau=0$: Grain = 5 % GB = 5 %
 $\tau=400$: Grain \approx 1 % GB \approx 16 %
 $\tau=5000$: Grain \approx 3 % GB \approx 18 %



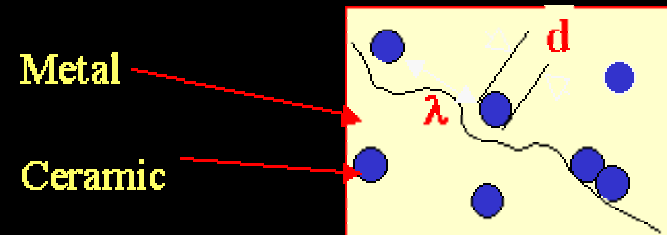
Model predicts significant grain growth retardation with 20% solute at gb
Experimental validation planned with PVD structures



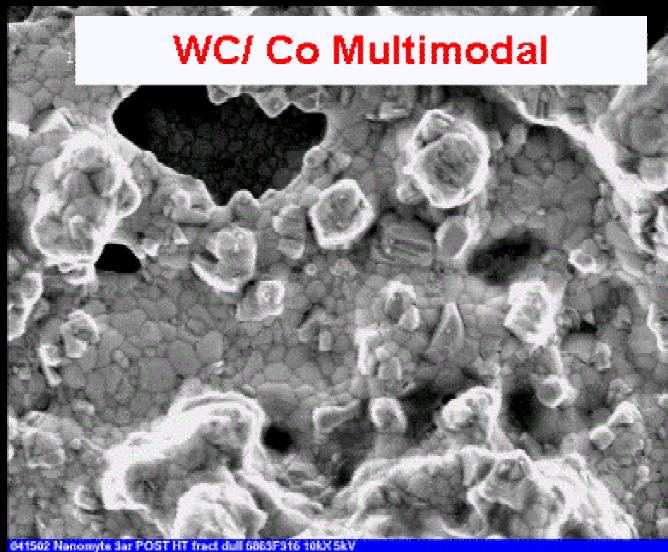
Wear resistance = f (H, K_c)

H = Hardness: $f(\lambda^{-1/2})$

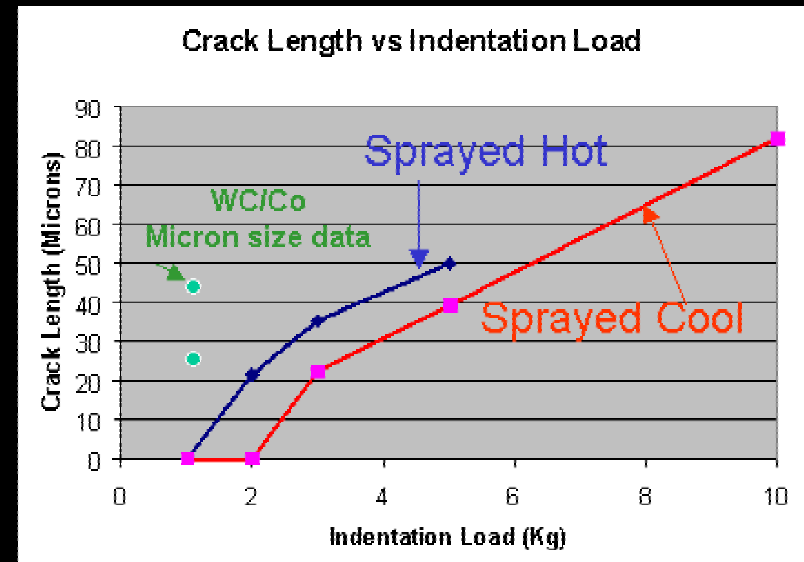
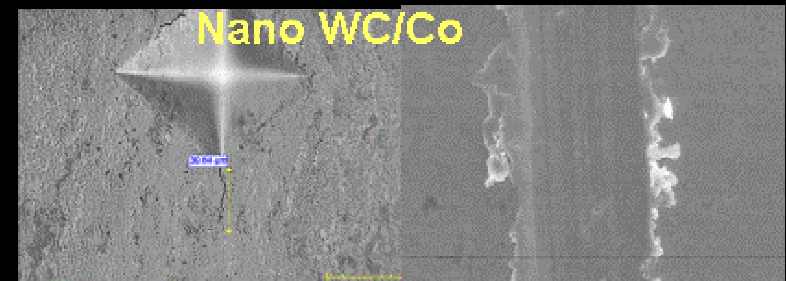
K_c = Fracture toughness: $f(\lambda/d)$



Thermal Sprayed WC/Co Coating



SEM of Fracture surface



High wear resistance and toughness obtained by nanostructured coatings



**Explore
stability &
strength in
materials with
broad-based
impact**



Dispersed

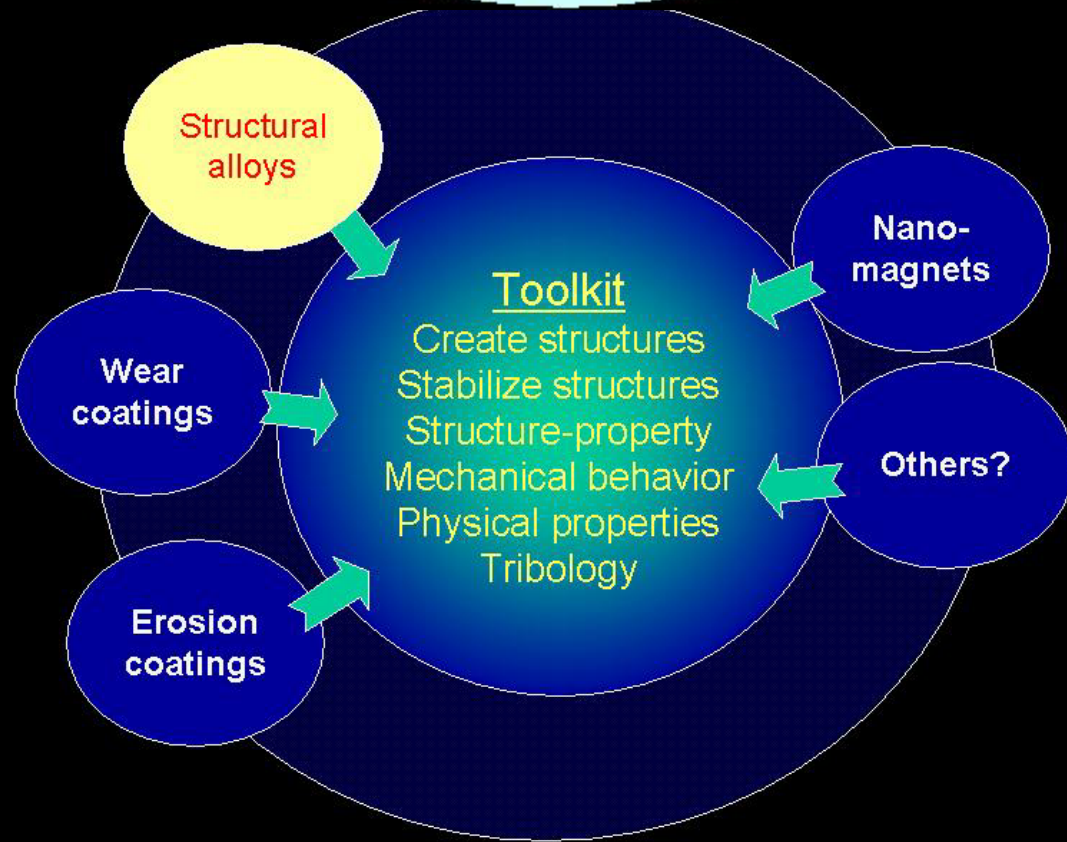
**Structural
Alloys**

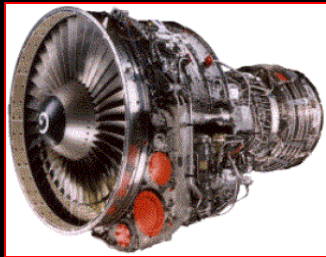
Multilayers

**Metal/Metal
Metal/Ceramics**

**Functional
Coatings**

**Beyond
structural
applications??**





Aircraft Engines



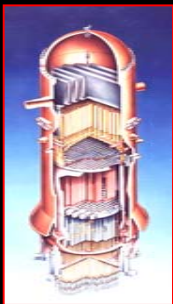
Gas Turbines



Medical Systems



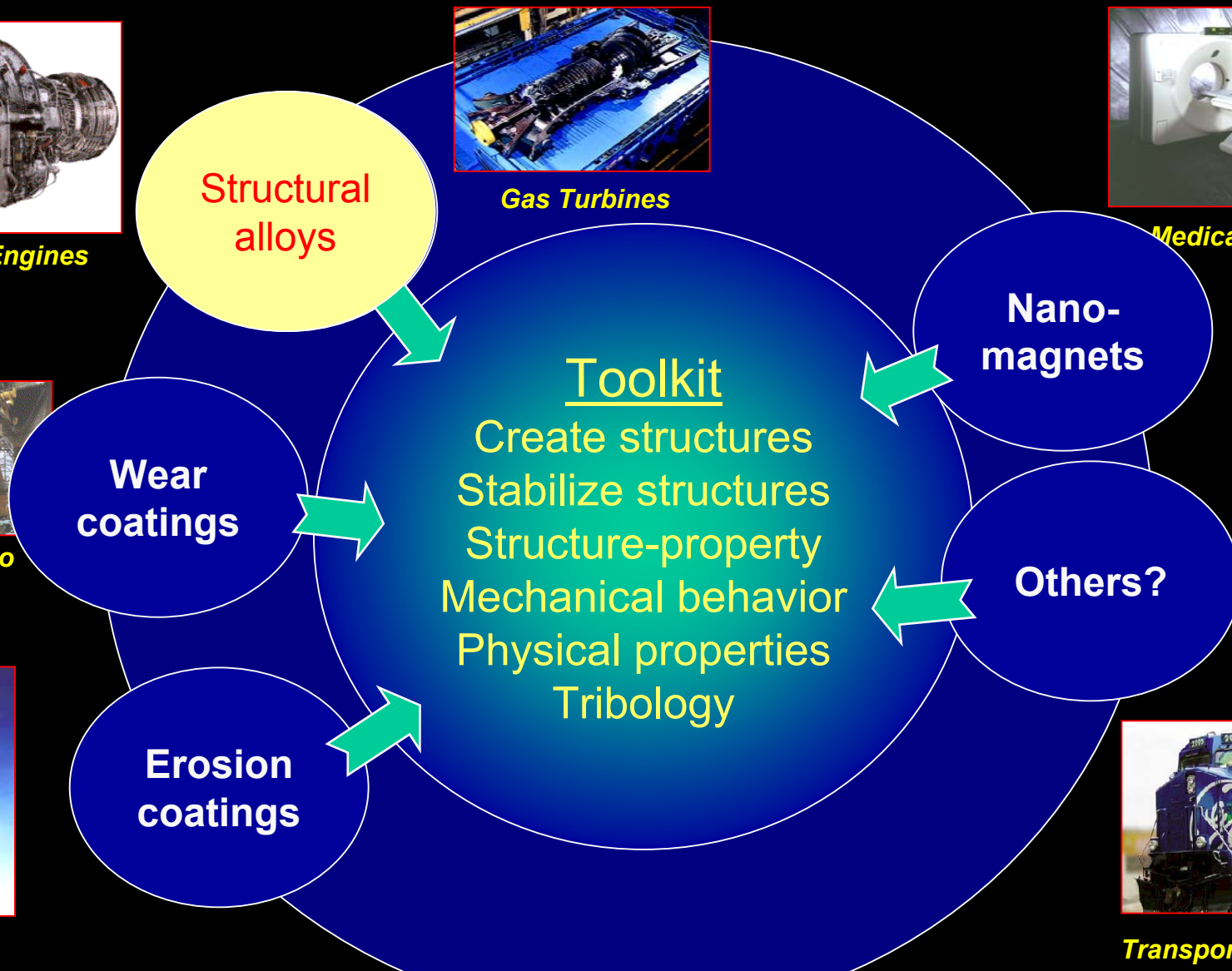
GE Hydro



GENE



Transportation System



Enabler for Multiple Applications



- *Kanchan Kumari – GEGR, Bangalore*
- *Dheepa Srinivasan – GEGR, Bangalore*
- *Michael Larsen - GEGR, Niskayuna*
- *Michelle Othon - GEGR, Niskayuna*
- *Ann Ritter - GEGR, Niskayuna*
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- *Yunzhi Wang - Ohio State University*
- *Hamish Fraser - Ohio State University*